



Components, Packaging, and Manufacturing Technology Society Newsletter



THE GLOBAL SOCIETY FOR MICROELECTRONICS SYSTEMS PACKAGING

VOL. 33 NO. 1, MARCH 2010, ISSN 1077-2999

www.cpmt.org

www.ewh.ieee.org/soc/cpmt/newsletter

President's Column....



Dr. William T. Chen
IEEE Fellow
President, IEEE CPMT Society
Santa Clara, CA, USA
wt-chen@ieee.org

The past year, 2009, was undoubtedly a tough year. However, economic news covering the first weeks of 2010 has reported that the great 2008 – 2009 economic depression has hit the bottom, and recovery is now in full mode. Despite this brighter news, the job situation continues to be dismal for many people, including some in our sector of the industry. We are extremely hopeful that the electronics industry will rebound vigorously throughout 2010, and that the job picture will improve too. One good sign is the excitement generated by a slew of new electronic products on the horizon. Many were unveiled at the Consumer Electronics Show (CES) in Las Vegas in early January, and included 3D TVs and Cell TV, tablets, e-book readers, as well as new generations of smart phones, ultrathin laptops, new generation netbooks, and pocket PCs.

Following CES was the International Auto Show held in Detroit. While I seldom pay much attention to new cars, it does seem that every car manufacturer is increasingly investing in sophisticated electronics in order to create hybrid, green, electric, and intelligent vehicles, which meet the expectations of today's environmentally conscious drivers. Beyond automotive, the role of electronics is also continuing to gain momentum, and strongly influence the rise of emerging technologies and applications, such as green electric power drive trains, internet-based electronic networks in the home, and much more. In fact, we are seeing strong indication of a pervasive electronics trend expanding from consumer to transportation and safety. What does this mean? In my mind, "mobility", in whatever form, will be the factor that drives the electronic industry. Fortunately for us, there has been a great surge of innovation and invention across the packaging technologies spectrum, from 3D



Perhaps Professor Brown is getting too intense with his IEEE Student Recruitment

NEWSLETTER SUBMISSION DEADLINES:

15 May 2010

15 August 2010

15 November 2010

15 February 2011

Submit all material to nsltr-input@cpmt.org

President's Column.... (cont.)

packaging, including 3D-IC - TSV, wafer level packaging, new generations of wirebond and flip chip technologies, and many versions of SiP and PoP. Electronic packaging stands at the crucial stages of the electronic product supply chain in product design, development and manufacturing technology. As a true-blue packaging technologist at heart, I am optimistic that packaging is and will be the major and crucial enabler and competitive edge to the growing global "mobility" and "pervasive" electronic product market.

As we welcome the New Year, I would like to mention some important changes in the CPMT neighborhood. I have had the privilege of writing this column for four years as the President of the Society. This is my last President's message. In November 2009, the Board of Governors (BoG) elected a new slate of officers for the Society for 2010 - 2011. They are:

PRESIDENT -- Rolf Aschenbrenner

VICE PRESIDENT -- N. Rao Bonda (incumbent)

VICE PRESIDENT -- Jie Xue

VICE PRESIDENT, PUBLICATIONS -- R. Wayne Johnson (incumbent)

VICE PRESIDENT, EDUCATION -- Kitty Pearsall

VICE PRESIDENT, FINANCE -- Thomas G. Reynolds III (incumbent)

Together with the BoG, this talented, dedicated, and eclectic team will lead the CPMT Society into 2010, and beyond. In our profession, technological innovation is at the heart of progress. The CPMT Society value propositions are all about enabling our membership and stakeholders to cultivate the knowledge, tools and people network to succeed in this uncertain world. They will be steering the directions of the value propositions in your service. We wish them great success.

Lastly, I would like to extend my most sincere thanks to the CPMT Society, the BoG, and many friends for the great support received during my term as President over the past four years.

CPMT Society News....

INTRODUCING YOUR CPMT SOCIETY OFFICERS FOR 2010-2011

Every two years, the CPMT Society Board of Governors elects a President and five Vice Presidents to serve a two-year term of office. Following are photos and biographies of the Officers elected for 2010 through 2011.

President:

ROLF ASCHENBRENNER



Rolf Aschenbrenner (M'97, SM '04) was born in Buchen, Germany, in 1961. He received the B.S. degree in mechanical engineering from the University for Applied Science, Gießen, Germany, in 1986 and the M.S. degree in physics from the University of Gießen, Germany, in 1991.

From 1991 to 1992 he worked at the University of Gießen in the area of new materials and was engaged in a project for the German Space Lab Mission D2. In 1993 he joined the Research Center for Microperipheral Technologies at the Technical University of Berlin, working in the area of electroless metal deposition. Since March 1994 he has been employed at the Fraunhofer Institute for Reliability and Microintegration Berlin (IZM) and from 2000 until 2006 he was Deputy Director of the IZM. He is presently department head of the largest department of the Fraunhofer IZM "System Integration and Interconnections Technologies".

Rolf Aschenbrenner's research work has spanned from manufacturing process fundamentals in adhesive joining to applied manufacturing problems. Broadening his research contributions beyond those are made in thin and flexible electronic assemblies and development and analysis of innovative process technologies for all aspects of system level packaging.

He has authored and co-authored more than 100 articles in journals or proceedings in the area of electronic packaging and he holds more than 14 patents in the field of microelectronic packaging. In 1995 he obtained the Best Paper Award as the main author from the Surface Mount International Conference (SMI) in San Jose. He also co-authored a number of papers that received Best Paper Awards.

In January 2005 he received the "iNEMI International Recognition Award" which was presented during the Fraunhofer Packaging Day.

In terms of professional services, Rolf Aschenbrenner has taken roles as a member of the Board of Governors for the IEEE CPMT Society. Until spring 2009 he was also a member of the Board of IMAPS Germany.

He was General Chair of the first International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics (Polytronic) in 2001.

In 2000 he was the Program Chair of the European VLSI Packaging Workshop in 2001 and of the IEEE European System Packaging Workshop. He also served as a member on several technical committees including ISEPT, Materials Conference, Adhesives in Electronics, EMAP, EPTC, Interpack and Electronic Goes Green.